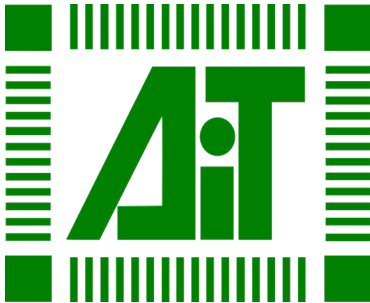


EXHIBITOR LISTINGS



AI Technology, Inc.

AI Technology, Inc. has more than 25 years of experience and successes in helping military, aerospace, computer, and super-computer manufacturers with thermal compound and thermal interface materials for building some of the most reliable electronic devices and computers. Since pioneering the use of flexible epoxy technology for microelectronic packaging in 1985, AI Technology, Inc. has been one of the leading forces in development of patented applications of advanced material and adhesive solutions for electronic interconnection and packaging. The company continues to provide adhesive solutions for component and substrate bonding for both military and commercial applications. It's thermal interface material solutions of patented phase-change thermal pads, thermal grease and gels and thermal adhesives set many bench marks of performance and reliability for power semiconductor and modules, computer and communication electronics.



Analysis Tech

www.analysisstech.com

Semiconductor Thermal Testers: Complete measurement systems for device thermal resistance, impedance, & die-attach quality using transient & steady state electrical-junction temperature-measurement. Transient structure function analysis is used to delineate internal-package resistances & measure Rjc via JEDEC 51-14. Power Cycling systems for device life-testing with automatic monitoring of thermal deterioration with age. Test services offered. Thermal Interface Material Testers: ASTM D5470 based testers offering fast & accurate measurement of thermal conductivity & contact resistance of electronic-packaging materials over a wide range of thickness, pressure, & temperature. Test services offered. Event Detectors: Electrical reliability-testers for passive interconnects including solder joints & connectors, with easy integration to thermal-cycle, drop-test, shock, and vibration gear; based on JEDEC and IPC standards for interconnect reliability testing



Alpha Novatech, Inc.

Alpha Novatech, Inc. is your partner for Thermal Solutions. We offer a wide variety of standard heat sinks and accessories. Our product line includes natural convection, forced convection, and active heat sinks. We also offer various attachment methods and hardware for almost any application. In addition, we can offer free heat sink thermal simulations. Standard or custom heat sinks in prototype to production quantities Quick and easy customization without NRE fees, while featuring short lead times Standard parts are carried in stock Lead time for custom parts of 1-2 weeks is possible for initial quantities.



ANSYS

ANSYS is the leading provider of electronic cooling, electromagnetic field, circuit and system simulation software for the design of high-performance electronic equipment. Companies throughout the world rely on ANSYS software to solve thermal integrity, mechanical reliability, signal integrity, power integrity and EMI challenges in IC, package and PCB and perform power optimization in custom IC's. Ansys develops open and flexible simulation solutions that enable users to simulate design performance directly on the desktop, providing a common platform for fast, efficient and cost-effective product development, from design concept to final-stage testing and performance validation. Engineers rely on ANSYS to achieve first-pass system success when designing mobile communication devices, broadband networking components and systems, integrated circuits (ICs), printed circuit boards (PCBs) and electromechanical systems. ANSYS' unique multiphysics platform provides a highly-accurate design flow for fast, efficient and simulation driven product development.

EXHIBITOR LISTINGS



AOS Thermal Compounds

AOS Thermal Compounds developed the first non-silicone thermal interface materials for AT&T in the 1960's. Today we manufacture the lowest thermal resistance and pump-out resistant thermal greases, unique Micro-Faze thermal pads, and a high performance and economical line of Sure-Form gap fillers.



Boyd Corporation

Boyd Corporation has over 90 years of customer-focused performance success and is a global leader in advanced sealing, thermal management and protection solutions. Aavid, Thermal Division of Boyd Corporation has a long history of developing, designing, testing, optimizing, and fabricating reliable high-performance cooling systems across all industries. By choosing, integrating, or developing the right technology, Boyd delivers solutions that can increase power, improve functionality and reliability, and reduce the cost and size of our customers' applications.



AR Brown

AR Brown is a provider of Aluminum Nitride Powder - high thermal conductivity, low viscosity, high filling rate - As manufacturers, we produce in-house, consistently enabling a stable supply of high-quality products. Compared to spherical products, it has a high filling property and can be expected to improve the properties of resin products with high thermal conductivity.



Cadence Design Systems, Inc.

Cadence, with its software, hardware and semiconductor IP enables electronic systems and semiconductor companies to create the innovative end products that are transforming the way people live, work and play. The company's Intelligent System Design strategy helps customers develop differentiated products—from chips to boards to Intelligent systems—in mobile, consumer, cloud, data center, automotive, aerospace, IoT, industrial and other market segments. Cadence is showcasing Celsius™ Thermal Solver, the industry's first complete electro-thermal co-simulation solution at SEMI-THERM 2020 in San Jose, California. Learn more at www.cadence.com



A New York State Center of Excellence
BINGHAMTON UNIVERSITY

Binghamton University

S3IP brings together teams of experts from industry and academia to address pressing real-world problems in the systems integration and manufacturing of electronics. Our research centers focus on topics related to electronics packaging, flexible electronics, heterogeneous integration, energy-efficient electronic systems and energy harvesting and storage. Binghamton University, the premier public university in the Northeast, is home to S3IP, a New York State Center of Excellence. Our PhD-level staff members and affiliated faculty, in 6 constituent research centers and 9 laboratories, are ready to assist companies in New York State and beyond with collaborative problem solving. As a result of our combined efforts, our industry partners have reported over \$1.5 billion of economic benefit.



CEJN North America

CEJN North America, the Quick Connect Solution Provider, delivers couplings and solutions for your liquid cooling needs. Our Leak-Free, Non-Drip coupling series offers high flow and minimal pressure drop; and Blind Mating options range from DN 3 to DN 19. CEJN's new UltraFlow Series features an extremely high flow combined with an unequalled low pressure drop. Customized solutions are also available. At CEJN, we develop our products for a future in liquid cooled data centers. Contact us: PHONE: 847-263-7200, by email: customer.service.usa@cejn.com, or via www.cejn.us.

EXHIBITOR LISTINGS



Celsia

Celsia specializes in custom heat sink design and manufacturing using liquid two-phase devices: heat pipes and vapor chambers. Through its US headquarters and Taiwan design & production facility, the company's goal is to deliver fast, affordable, and reliable thermal solutions for the most demanding applications including high density electronics, performance CPU / GPU, amplifiers, HBLEDs, ASICs, and rugged systems. In recent years, Celsia has shipped over 2.5 million thermal assemblies to a global custom base in the telecommunications, computer, test equipment, defense, laser, and medical markets.



CPC

CPC thinks beyond the point of connection to help protect valuable electronics. Designed specifically for liquid cooling applications, rugged couplings withstand long periods of connection yet disconnect reliably without drips.



Chroma ATE Inc.

Chroma ATE Inc. Irvine Ca., is a world-leading designer and manufacturer of complete turn-key, IC thermal management and automated IC Handling solutions. Specializing in integrated and fully automated turn-key electronic test and MES solutions for the semiconductor, front and back-end test spaces. Chroma is driven to provide unique, tailored solutions, and technical support to help our US-based customers excel in today's high demanding environment.



Degree Controls

Degree Controls is the leading manufacturer of miniature, board-mount air velocity and temperature sensors for embedded electronics applications, where power density is high, and thermal reliability is paramount. Our sensors are built into high-end electronics all over the world, reporting air velocity and temperature in real time, while directly speed-controlling fans or impellers to eliminate the need for fan controllers.

Our line of research grade, multi-point air velocity sensors with USB plug and play connectivity, are used by electronic and product designers around the world for maximizing cooling, thermal efficiency and reliability. Up to 200 air velocity sensors can be placed on PCB assemblies, or in the chassis, to study air velocity in real time, and prove out thermal engineering designs. Based in New Hampshire, USA, Degree Controls brings 25+ years of thermal engineering and sensor design experience to the electronics market.



COFAN USA

At COFAN USA, we keep your hot technology cool. COFAN USA is an industry leading manufacturer in thermal management solutions with inhouse thermal engineering team providing thermal simulation service and consultation to our customers. With more than 20 years of expertise, we've had the pleasure of serving a diverse customer base in many industries. We offer quick turnaround product inquiries and prototyping services. We pride ourselves in giving the best possible customer service, the highest quality products with the shortest lead time, and competitive pricing in the industry. To learn more about us, please visit www.cofan-usa.com



Delta Fan and Thermal Products Group

The Delta Fan and Thermal Products Group designs and builds innovative cooling systems that perform to the highest standards – even in harsh environments.

The Delta Fan and Thermal product line includes a full range of axial fans, blowers, heat pipes, vapor chambers and liquid cooler products.

Our Delta-exclusive patented design and innovative structure boosts cooling performance and reduces system noise. Delta fans and thermal products are sold globally, serving an array of industries and organizations. Highly efficient cooling solutions can be customized to suit the needs of virtually any business.

EXHIBITOR LISTINGS

Dexerials

Dexerials Corporation

Dexerials Corporation creates advanced materials for a variety of different applications by utilizing its unique set of functional materials, process solutions, and customized technology. Dexerials is promoting three different types of thermal conductive sheets: silicone, acrylic, and carbon fiber. The silicone type features high thermal conductivity and flexibility while the acrylic type does not generate low molecular weight siloxanes (which causes contact failure in electronic devices). The carbon fiber type, with extremely high thermal conductivity of up to 35 W/(m • K), is an ideal fit for thermal countermeasures in high performance CPUs and power ICs. For more information, please visit www.dexerials.jp/en.



Dynatron Corporation

Dynatron Corporation, an industry leader in thermal solutions spanning a wide spectrum of consumer to enterprise products. With missions of CPU coolers sold worldwide since 1995. Dynatron has established its reputation over the years and continues to reinforce it with world class support and inventive ways to keep critical systems operating.

It is also the first company to invent a uniquely designed radiator equipped with a built-in pump into the liquid cooler. Coupled with an integrated Skived fin and its proprietary Vapor Chamber technology into a heatsink, has raised the standard in liquid cooling.

ebm papst

ebm-papst is an innovator and market leader in fans, blowers, and motors with core competencies in motor technology, aerodynamics, and electronics. With over 15,000 products, we provide solutions to a wide range of markets including Air-conditioning and Ventilation, Appliance, Automotive, Commercial Refrigeration, Heating, Industrial, IT / Telecom, Lighting & Digital Signage, Medical, Transportation and more.

electronics COOLING

Electronics Cooling

Electronics Cooling magazine has been providing a technical data column since 1997 with the intent of providing you, the readers, with pertinent material properties for use in thermal analyses. We have largely covered the most common materials and their associated thermal properties used in electronics packaging.

ITEM Media publishes a portfolio of digital and print magazines within the electronics industry. Our titles are available in a variety of electronic and printed media formats, including digital magazines, e-newsletters, social media feeds, forums, content marketing tools and printed magazines.

Electronic Cooling Solutions inc

2344B Walsh Avenue, Building F, Santa Clara, CA 95051 (408) 738-8331

ECS

ECS provides services for companies in a wide variety of industries and applications. Our customers develop products for the avionics, consumer, computing, medical, networking and telecommunications industries. Special needs can also be addressed, such as cooling the electronics for a unique telescope, and the thermal issues in manufacturing processes.

Since its founding, ECS has established a reputation for excellent service to its customers, providing high-quality and cost-effective solutions. Each member of the team is customer-driven and brings a combination of design, analysis and test skills to the issues faced by our customers. Several members of the team have 15 or more years of experience solving thermal problems in a product development or research environment.

Today, ECS is a leading-edge company in thermal management services and is based in the heart of Silicon Valley.

EXHIBITOR LISTINGS



DE BEERS GROUP

Element Six

Who we are: Element Six is a global leader in the design, development and production of synthetic diamond and tungsten carbide supermaterials. Part of the De Beers Group, we employ over 1,900 people. Our primary manufacturing sites are located in the UK, Ireland, Germany, South Africa, and the US.

Our mission: We strive to deliver extreme performance through the development of cutting-edge synthetic diamond and tungsten carbide solutions.

Our history: Since 1959, our focus has been on developing the diamond synthesis process to enable innovative synthetic diamond and tungsten carbide solutions. As well as being the planet's hardest material, diamond's extreme and diverse properties give it high tensile strength, chemical inertness, broad optical transmission and very high thermal conductivity.

Find out more about us at e6.com



Fujipoly

Fujipoly is a world leader in the manufacture of Sarcon® Thermal Interface Materials, which are used to help keep sensitive electronic components cool by eliminating the air gap between the component and heat sink. Our products range in thermal conductivity from 1.0m watt/m-K to 17 watt/m-K, offering some of the lowest thermal resistance in the industry. Our product line-up consists of soft Gap Filler Pads, Conformable Putties, Form-In-Place Gap Fill Materials, as well as custom and standard die-cut thin film materials. Our wide range of material types, coupled with the widest range of thermal conductivity, allows us to meet most design criteria. Fujipoly has nine locations in North America, Europe, and Asia making it easy for us to assist our customers at the local level.



Future Facilities

We set Future Facilities up to deliver the power of engineering simulation into the hands of an emerging data center industry. We created a tool optimized for data centers, designed to be used by the DC professional, and made it powerful, intelligent, automated and connected. Five years later, we tuned our technology to deliver the same benefits to the thermal management of electronics and provide an integrated toolset for these two converging industries. We develop engineering simulation software that allows our customers to quantify and qualify business decisions balancing risk against cost. Our offering covers the full spectrum starting from electronics design to data center design and operations. Our software provides a safe, offline environment in which to create virtual prototypes, troubleshoot existing designs and run what-if scenarios for future configurations.



Indium Corporation

Indium Corporation is a premier materials manufacturer and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, Indium has global technical support and factories located in China, Malaysia, Singapore, South Korea, the United Kingdom, and the USA.

For more information about Indium Corporation, visit www.indium.com or email abrown@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.facebook.com/indium or @IndiumCorp.



InfraTec

The Dresden-based company InfraTec GmbH Infrarotsensorik und Messtechnik has been a specialist for products and services in the field of infrared technology for 25 years. Now about 220 staff are employed. In the business division of sensor systems, custom-made components are produced on more than 1.000 m² of clean room space – especially pyroelectrical infrared detectors – for clients worldwide. With its business division of infrared measurement InfraTec ranks among the large suppliers of thermography and non-military thermal imaging. InfraTec has been supplying thermal imaging technology like its high-end camera series Imager® to demanding customers. Specific solutions tailored to electronic and microelectronic testing have been developed which today suit the needs of customers in the value chain of LED development and manufacturing.

EXHIBITOR LISTINGS



Jones Tech

Jones Tech provides creative thermal and EMI solutions to improve the reliability of electronic equipment. Established in 1997, with its rich R&D resources and manufacturing experience, Jones Tech has been serving consumer electronics, telecommunications, IT, medical, and renewable energy customers. We are a long-term supplier to 4 of the top 5 Silicon Valley companies. Our thermal interface material (TIM) includes thermal pads, gel, grease, thermal phase change materials (PCM), and graphite TIM. For heat spreaders, we are a leading supplier of synthetic and natural graphite. We have in-house rotary and flatbed die-cutting capabilities. For heat storage materials, we offer PCM pads, gel and potting material. We can help with manual or robotic dispensing. Additionally, we help solve problems with EMI and RF related components.



Klinger IGI

Klinger IGI is an AS9100 / ISO 9001-2015 / ITAR registered manufacturer, specializing in precision cut thermal interface and gap pads, EMI/RFI shields, acoustic and vibration dampers, washers and spacers, filters, and custom gaskets and seals for OEMs and Tier 1s in the highly regulated aerospace, electronics, medical, and energy industries. Klinger IGI delivers total solutions with a large selection of material options, proven manufacturing technologies and simple integration of manufactured production parts with tight tolerances. We offer expertise in selecting the most cost-effective material solutions while supporting the design of your parts with effective manufacturing and assembly operations.



Laird Performance Materials

Laird Performance Materials enables high-performance electronics. We create advanced protection solutions for electronic components and systems. World-leading technology brands rely on us for improved protection, higher performance and reliability, custom structural designs and faster time-to-market. We solve design issues through innovative products such as EMI suppression or absorption materials, thermal interface materials, structural and precision metals, magnetic ceramic products, and multi-functional solutions. This latter product family solves multiple EMI, thermal, and structural design issues simultaneously using a single process solution.



LISAT

LISAT, manufacturer of Thermal Interface Material & EMI products. HQ in U.S., LISAT have operations in Asia. In U.S., we provide Thermal Management Solution to customers & work with R&D Engineers at Design Centres. We provide technical support & samples to our customers to test our materials. Our Asia operations provide manufacturing, converting, technical & sales to customers' worldwide. Our products : TIM Pad, Insulator, Silicon Free TIM, Gel, Grease, Mylar, Graphite, Conductive Plastic, Conductive Elastomer, Fabric-Over-Foam, Microwave Absorbing Material, Metal Finger Stock, EMI Shielding Solution, Switching Power Supply, Desktop & Wall Mount Adaptor, Metal Core PCB, Ceramic PCB. Email alan@lisat.net



Long Win

Long Win specializes in research, design, manufacture and service of scientific instruments for thermal managing, material & fluid mechanic and educational fields. Long Win holds a leading position on research, measurement and inspection apparatus for the electronic cooling market. Some of their product lines include thermal-related measurement apparatus for fan performance, TIMs, cooler modules, heat pipes, vapor chambers, IC packages, LEDs, liquid cooling, thermal and flow test for servers, racks and data center, and natural-convection simulation. They have more than 100 types of apparatus in their 18,000 sq. ft. lab which is located in Taiwan and a lab based in Livermore, California.



Ingenuity for life

Mentor, a Siemens business

Siemens PLM Simcenter portfolio includes a range of simulation software and test equipment solutions to aid development of a virtual digital twin of a product for improved design and lifecycle management. This portfolio now includes 30+ year industry leading Simcenter Flotherm electronics cooling software product family and Simcenter T3STER thermal test hardware solutions from Mentor, a Siemens business.

Find out about the latest in enhancements to Simcenter Flotherm and Simcenter Flotherm XT at SEMI-THERM, and seek more information on other simulation tools in the portfolio incl. multi-physics simulation software (Simcenter STAR-CCM+), CFD for designers (Simcenter FLOEFD).

In semiconductor thermal measurement, characterization and thermal reliability, find out the latest on Simcenter T3STER test solution family. This includes latest developments in thermal measurement to support automatic thermal simulation model calibration and LED multi-domain models, TIM material testing, and power semiconductor thermal reliability testing (SIMCENTER POWERTESTER range).

EXHIBITOR LISTINGS



Man Zai

As a leader in electronic liquid cooling system, Man Zai offers a wide range of thermal modules for CPU, VGA, LED, Bio-Chemical and automotive electronic device. The thermal team is equipped with state of the art hardware and software, which includes wind tunnel testing, hydraulic test equipment, simulation software, helium & air leakage test equipment and ultra-high-speed pre-filling technology. We are able to establish long-term relationships with several world-wide famous brand names. The quality system and sophisticated R&D capability in Man Zai will provide our customers the best thermal solution.



MSC Software

MSC Software develops simulation software technology that enables engineers to validate and optimize their designs using virtual prototypes. Our CFD solutions are characterized by their user-friendly interfaces, high accuracy, and high efficiency. Customers in almost every part of manufacturing use our software to complement, and in some cases even replace the physical prototype "build and test" process that has traditionally been used in product design.



Thermexit

Nanoramic Thermexit™ is a line of high-end thermal interface gap filler pads. Nanoramic's gap fillers are a non-reactive, non-silicon, no cure system featuring high thermal conductivity and high thermal stability. Nanoramic produces 2 novel product lines, a High Performance TIM Gap Filler and an Electrically Insulating TIM Gap Filler.



NeoGraf Solutions, LLC

NeoGraf Solutions, LLC, a world leader in graphite materials science, has been manufacturing carbon and graphite products for over 135 years in Lakewood, Ohio. Today, our high-performance products are used in a variety of demanding applications in a diverse array of industries. We specialize in development and manufacture of high quality natural and synthetic graphite sheets and powders used in the latest consumer electronic devices, building & construction materials, transportation, and sealing & gasketing. With internal research, development, and manufacturing capabilities, NeoGraf provides high quality products, environmentally sustainable solutions, and new opportunities for our customers.



NETZSCH Instruments

NETZSCH Instruments provides a complete instrument line and laboratory testing for thermal analysis with industry leading products for evolved gas analysis (QMS, FT-IR, GC-MS). When it comes to Thermal Analysis, Calorimetry (adiabatic & reaction) and the determination of Thermophysical Properties, NETZSCH has it covered. Our 50+ years of applications experience, broad state-of-the-art product line and comprehensive service offerings ensure that our solutions will not only meet your every requirement but also exceed your every expectation.



Schlegel

Schlegel Electronic Materials (SEM) invented highly conductive fabric over foam shielding gaskets in 1987, marking a major breakthrough for the electromagnetic interference shielding of electronic enclosures and has become the pre-eminent manufacturer of electromagnetic interference (EMI) shielding products.

SEM offers a full range of EMI shielding products including gaskets, Thermal Interface Materials, I/O backplane shielding gaskets, BeCu Fingerstock, and conductive tapes, laminates, and a newly developed line of absorbers. These products enable the computer, telecommunications, military, medical and electronics industries to meet global requirements for electromagnetic compatibility (EMC). From concept to production, SEM's complete portfolio of shielding products combines highly conductive materials with flexible foams and coatings to provide the latest EMI containment solutions.

EXHIBITOR LISTINGS



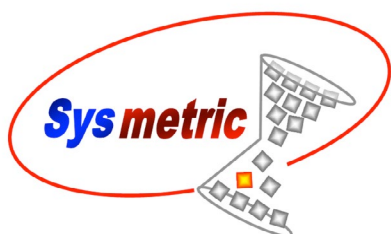
Shin-Etsu MicroSi

Shin-Etsu MicroSi is the leader in Thermal Interface Material, and we have developed an extensive line of Molding Compounds, Encapsulents, Silicon and Epoxy coatings along with die Attachment Materials. The quality of our thermal interface material is among the most advanced in semiconductor manufacturing and has a wide range of use in thermal interface material applications. Some of which include thermal gels and grease, phase change materials, and high hardness silicone rubber pads. Shin-Etsu products are delivered globally to many major and minor companies involved in the fabrication process of electronics and microelectronics.



Stäubli

Stäubli is an innovative mechatronics solutions provider with three dedicated activities: Connectors, Robotics and Textile. With a workforce of over 4500, Stäubli has a presence in 25 countries and agents in 50 countries around the world. As one of the leading manufacturers of quick connector systems, Stäubli covers connection needs for all types of fluids, gases and electrical power. These standard or specific products – including single and multiple connectors, tool changers and quick mold change systems – combine performance, quality, safety, dependability and durability.



Sysmetric

Sysmetric develops thermal management solutions for testing and validation engineers.

Sysmetric cooling systems aim to answer the new market demands to validate Silicon DUT (Device under test) under new validation temperature standards of 150W@-40 °C up to 1KWatt@ 125°C.

Specialized fields including:

- Semiconductor testing
- Medical devices
- Climate chambers
- Laser systems.



TCPoly, Inc.

TCPoly has developed ultra-high thermal conductivity composites and phase change materials that can be used to manufacture high performance heat transfer products on low-cost 3D printers including lightweight, corrosion resistant, and high-performance heat exchangers, heat sinks, cold plates, and heat conductive cases and enclosures. Their patented materials can achieve effective thermal conductivities greater than 50 W/m-K and can be formulated to be electrically insulating, thermochromic, and have tunable EDS/EMI properties. TCPoly is a total thermal solutions provider, offering a full suite of services from product design and testing to custom materials formulation and product production. Their production partners can make thousands of 3D printed parts per month and are constantly growing their capacity as additive manufacturing technology evolves.



TE Connectivity

TE Connectivity is a global technology and manufacturing leader creating a safer, sustainable, productive, and connected future. For over 75 years, its connectivity and sensor solutions have enabled advancements in transportation, industrial applications, medical technology, energy, data communications, and the home. With 78,000 employees, including more than 7,000 engineers, in nearly 150 countries, it ensures that every connection counts.

EXHIBITOR LISTINGS



T-Global Technology

T-Global Technology is dedicated to the development, manufacture and research of all-rounded thermal solution products. We provide our customers with thermal simulation, rapid sampling, customized products and professional technical support. With rich experience in research, development and marketing, T-Global is already become the designated and direct supplier of over 3,000 enterprises worldwide.



Thermal Engineering Associates

TEA is a company founded by Bernie Siegal, a 35+-year veteran and recognized technical leader in the semiconductor thermal field. The company's mission is to provide a central source for the products and services necessary for proper semiconductor thermal measurement and modeling and solutions to attendant thermal management problems. Through its own products and services, augmented by an extensive network of technical experts around the world, TEA can assist customers in finding solutions. The Tech Briefs and Hot Links pages provide useful information to those interested in semiconductor and electronics thermal issues. We welcome the opportunity to discuss your thermally-related measurement, modeling and/or management requirements.



ThermAvant Technologies

ThermAvant Technologies, LLC designs, develops and delivers custom thermal solutions to improve size, weight, performance and/or costs of advanced energy and technology platforms. The leading provider of Oscillating Heat Pipe products, ThermAvant also offers custom Cold Plates, Ejector Refrigerators, and Design & Engineering services.



ThermoAnalytics

ThermoAnalytics provides thermal solutions for complex vehicle engineering simulation. Our software, TAItherm, is the industry's most complete and flexible thermal modeling software, one that can predict the full range of temperature distribution in your product or system. TAItherm can model a variety of thermally sensitive components including transient brakes, underhood, exhaust and underbody simulation, HVAC, cabin, battery packs for HEV/EV, and more. ThermoAnalytics' rapid transient thermal analysis can couple to FEA and CFD software, a key component to an efficient design process. Our software is commonly used in the automotive, aerospace, heavy vehicle, and railway industry. ThermoAnalytics also offers advanced consulting services with our engineering teams that specialize in thermal, CFD, infrared simulation and testing.



W. L. Gore & Associates

W. L. Gore & Associates is a global materials science company dedicated to transforming industries and improving lives. We are a privately held company with a 60-year heritage of working together with each other and our customers to develop innovations that improve the world.

Gore has served the electronics industry for many years and we are excited to showcase our latest breakthrough material for thermal management in mobile electronic devices. Our thermal insulation material, GORE® Thermal Insulation, can help thermal engineers solve challenging hot spot issues in thin device designs. Please stop by our booth to learn more.



WACKER is a global silicone leader with a broad portfolio of products designed for the needs of the electronics industry. Our SEMICOSIL®, SilGel®, and ELASTOSIL® brands are globally recognized in the industry. Please stop by our booth and learn how our potting gels, adhesives, and newest thermal interface materials can help you meet your design challenges.